

In re Application of: Chad A. Cobbley et al.

Serial No.: 10/771,085

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STACKED DIE MODULE AND TECHNIQUES FOR FORMING A

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Group Art Unit:

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Examiner:

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Date

Sir:

RESPONSE

In response to the Official Action mailed on March 17, 2005, Applicants respectfully request reconsideration of the above-identified application in view of the remarks set forth below.